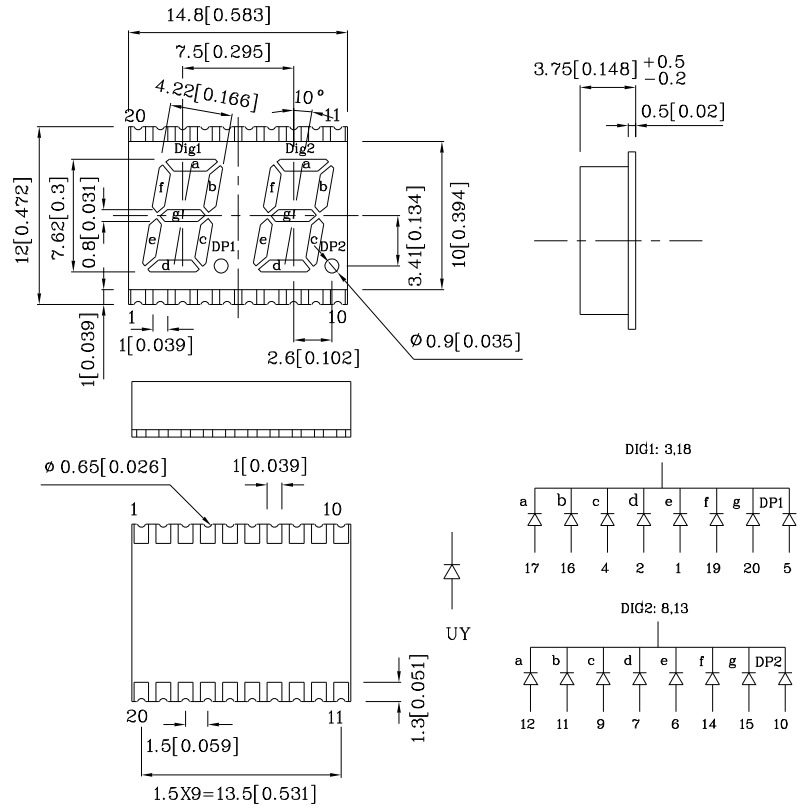


Features

- 0.3NCH DIGIT HEIGHT.
- LOW CURRENT OPERATION.
- EXCELLENT CHARACTER APPEARANCE.
- I.C. COMPATIBLE.
- MECHANICALLY RUGGED.
- GRAY FACE, WHITE SEGMENT.
- PACKAGE : 600PCS / REEL.
- RoHS COMPLIANT.



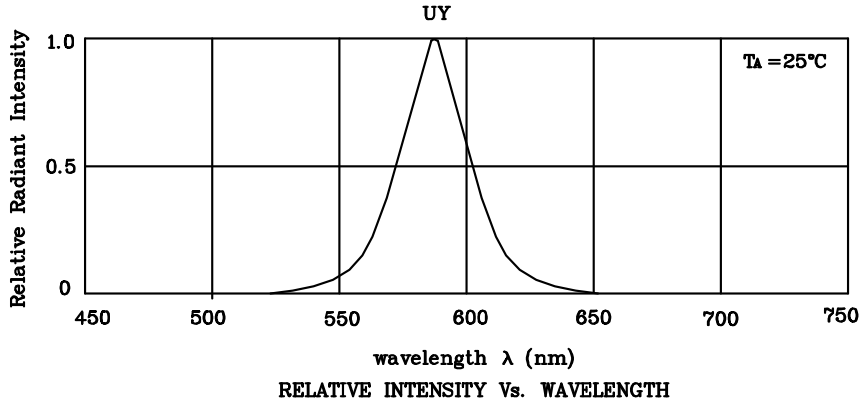
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ " unless otherwise noted.

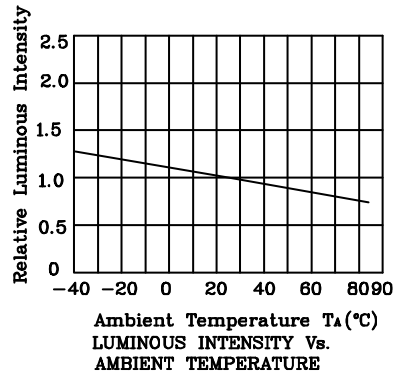
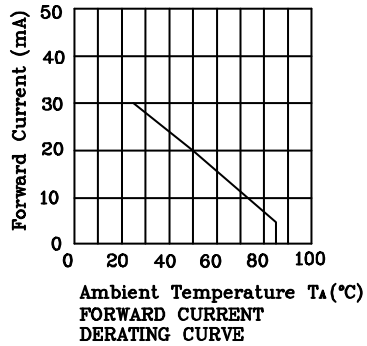
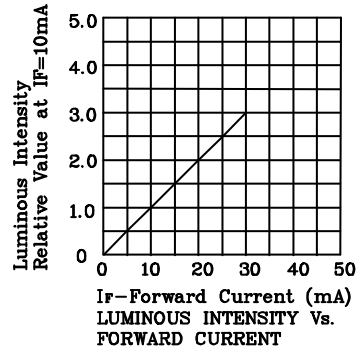
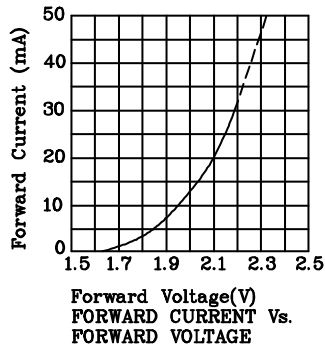
Absolute Maximum Ratings (TA=25°C)		UY (GaAsP/GaP)	Unit
Reverse Voltage	VR	5	V
Forward Current	IF	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	iFS	140	mA
Power Dissipation	PT	105	mW
Operating Temperature	TA	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	

Operating Characteristics (TA=25°C)		UY (GaAsP/GaP)	Unit
Forward Voltage (Typ.) (IF=10mA)	VF	1.95	V
Forward Voltage (Max.) (IF=10mA)	VF	2.5	V
Reverse Current (VR=5V)	IR	10	uA
Wavelength of Peak Emission (IF=10mA)	λ P	590	nm
Wavelength of Dominant Emission (IF=10mA)	λ D	588	nm
Spectral Line Full Width At Half-Maximum (IF=10mA)	Δλ	35	nm
Capacitance (VF=0V, f=1MHz)	C	20	pF

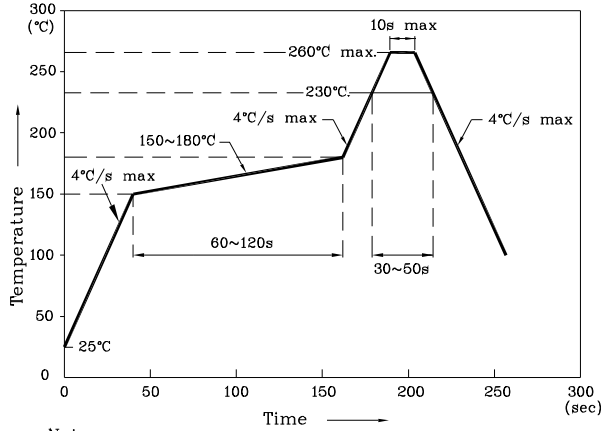
Part Number	Emitting Color	Emitting Material	Luminous Intensity (IF=10mA) ucd		Wavelength nm λ P	Description
			min.	typ.		
XZDUY07C2	Yellow	GaAsP/GaP	480	2280	590	Common Cathode, Rt. Hand Decimal



❖ UY



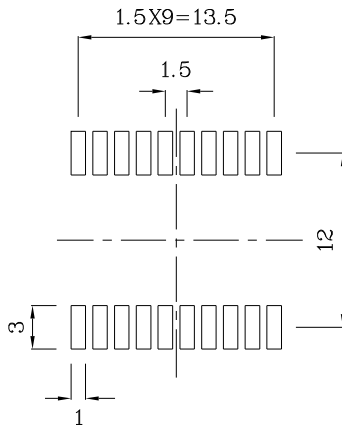
Reflow Soldering Profile For Lead-free SMT Process.



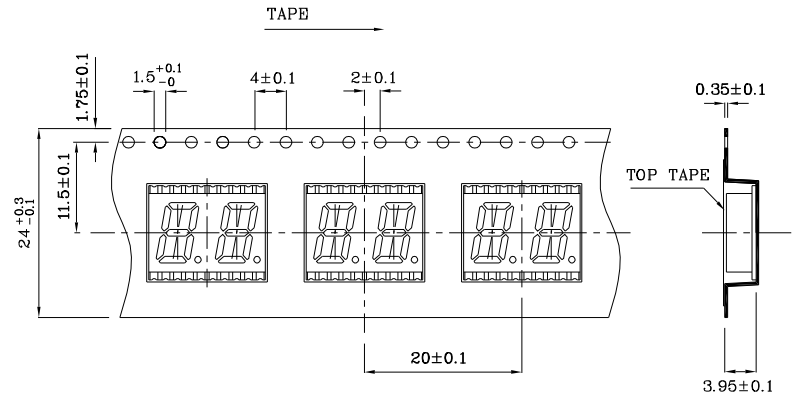
Notes:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C~260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

❖ Recommended Soldering Pattern
(Units : mm;Tolerance:± 0.15)



❖ Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.